# Microphone Pre-Amplifier with Digital Output

# FAN3852

#### Description

The FAN3852 integrates a pre-amplifier, LDO, and ADC that converts Electret Condenser Microphone (ECM) outputs to digital Pulse Density Modulation (PDM) data streams. The pre-amplifier accepts analog signals from the ECM and drives an over-sampled sigma delta Analog-to-Digital Converter (ADC) and outputs PDM data. The PDM digital audio has the advantage of noise rejection and easy interface to mobile handset processors.

The FAN3852 features an integrated LDO and is powered from the system supply rails up to 3.63 V, with low power consumption of only 0.85 mW and less than 20  $\mu$ W in Power–Down Mode.

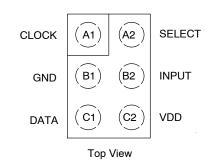


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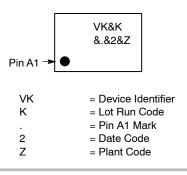


WLCSP-6 CASE 567TS



# PIN CONFIGURATION

### MARKING DIAGRAM



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

#### Features

- Optimized for Mobile Handset and Notebook PC Microphone Applications
- Accepts Input from Electret Condenser Microphones (ECM)
- Pulse Density Modulation (PDM) Output
- Standard 5–Wire Digital Interface
- Low Input Capacitance, High PSR, 20 kHz Pre-Amplifier
- Low–Power 1.5 µA Sleep Mode
- Typical 420 µA Supply Current
- SNR of 62 dB (A) for 16 dB Gain
- Total Harmonic Distortion 0.02%
- Input Clock Frequency Range of 1–4 MHz
- Integrated Low Drop–Out Regulator (LDO)
- Small 1.242 mm × 0.842 mm 6–Ball, 0.400 mm pitch standard WLCSP Package
- 1.5 kV HBM ESD on MIC Input

#### **Typical Applications**

- Electret Condenser Microphones with Digital Output
- Mobile Handset
- Headset Accessories
- Personal Computer (PC)

#### **ORDERING INFORMATION**

Part Number	rt Number Operating Temperature Range Package		Packing Method $^{\dagger}$
FAN3852UC16X	−40°C to 85°C	6 Ball, Wafer-Level Chip-Scale Package (WLCSP)	3000 Units/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### INTERNAL BLOCK DIAGRAM

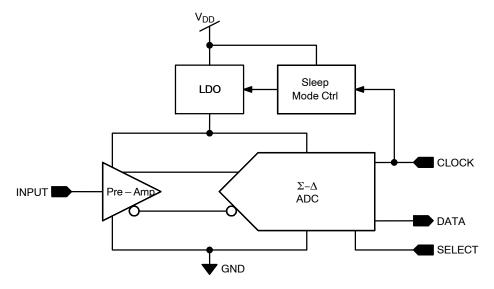


Figure 1. Block Diagram

#### Table 1. PIN DEFINITIONS

Pin #	Name	Туре	Description	
A1	CLOCK	Input	Clock Input	
B1	GND	Input	Ground Pin	
C1	DATA	Output	PDM Output – 1 Bit ADC	
A2	SELECT	Input	Rising or Falling Clock Edge Select	
B2	INPUT	Input	Microphone Input	
C2	VDD	Input	Device Power Pin	

#### Table 2. ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Min.	Max.	Unit
V <sub>DD</sub>	DC Supply Voltage	-0.3	4.0	V
V <sub>IO</sub>	Digital I/O	-0.3	V <sub>DD</sub> + 0.3	V
	Microphone Input	-0.3	2.2	
ESD	ESD Human Body Model, JESD22–A114, All Pins Except Microphone Input			kV
	Human Body Model, JESD2-A114 - Microphone Input	±1.5		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

This device is fabricated using CMOS technology and is therefore susceptible to damage from electrostatic discharges. Appropriate
precautions must be taken during handling and storage of this device to prevent exposure to ESD.

#### Table 3. RELIABILITY INFORMATION

Symbol	Rating	Min.	Тур.	Max.	Unit
Т <sub>Ј</sub>	Junction Temperature			+150	°C
T <sub>STG</sub>	Storage Temperature Range	-65		+125	°C
T <sub>RFLW</sub>	Peak Reflow Temperature			+260	°C
$\theta_{JA}$	Thermal Resistance, JEDEC Standard, Multilayer Test Boards, Still Air		90		°C/W

2.  $T_A = 25^{\circ}C$  unless otherwise specified

#### Table 4. RECOMMENDED OPERATING CONDITIONS

Symbol	mbol Rating		Тур.	Max.	Unit
T <sub>A</sub> Operating Temperature Range		-40		+85	°C
V <sub>DD</sub>	V <sub>DD</sub> Supply Voltage Range		1.80	3.63	V
T <sub>RF-CLK</sub>	Clock Rise and Fall Time			10	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### Table 5. DEVICE SPECIFIC ELECTRICAL CHARACTERISTICS

Symbol	Value	Min.	Тур.	Max.	Unit
SNR	Signal-to-Noise Ratio f <sub>IN</sub> = 1 kHz (1 Pa), A-Weighted		62		dB (A)
e <sub>N</sub>	Total Input RMS Noise 20 Hz to 20 kHz, A-Weighted		5.74	6.80	μV <sub>RMS</sub>
V <sub>IN</sub>	Maximum Input Signal f <sub>IN</sub> = 1 kHz, THD + N < 10%, Level = 0 V			448	mV <sub>PP</sub>

3. Guaranteed by characterization and/or design. Not production tested.

#### Table 6. ELECTRICAL CHARACTERISTICS

Unless otherwise specified, al limits are guaranteed for  $T_A = 25$  °C,  $V_{DD} = 1.8$  V,  $V_{IN} = 94$  dB (SPL) and  $f_{CLK} = 2.4$  MHz. Duty Cycle = 50% and  $C_{MIC} = 15$  pF

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
V <sub>DD</sub>	Supply Voltage Range		1.64	1.80	3.63	V
I <sub>DD</sub>	Supply Current	INPUT = AC Coupled to GND, CLOCK = On, No Load		420		μΑ
I <sub>SLEEP</sub>	Sleep Mode Current	f <sub>CLK</sub> = GND		1.50	8.0	μΑ
PSR	SR       Power Supply Rejection (Note 5)       INPUT = AC Coupled to GND, Test Signal on V <sub>DD</sub> = 217 Hz, Square Wave and Broadband Noise (Note 4), Both 100 mV <sub>P-P</sub>		-74		dBFS	
IN <sub>NOM</sub>	Nominal Sensitivity (Note 6)	INPUT = 94 dBSPL (1 Pa)		-26		dBFS
THD	Total Harmonic Distortion (Note 7)	f <sub>IN</sub> = 1 KHz, INPUT = -26 dBFS		0.02	0.20	%
THD+N	THD and Noise (Note 5)	50 Hz $\leq$ f <sub>IN</sub> $\leq$ 1 kHz, INPUT = -20 dBFS		0.2	1.0	%
		f <sub>IN</sub> = 1 KHz, INPUT = -5 dBFS		1.0	5.0	
		f <sub>IN</sub> = 1 KHz, INPUT = 0 dBFS		5.0	10.0	
C <sub>IN</sub>	Input Capacitance (Note 8)	INPUT		1.3		pF
R <sub>IN</sub>	Input Resistance (Note 8)	INPUT	>10			GΩ
V <sub>IL</sub>	CLOCK & SELECT Input Logic LOW Level				0.3	V

#### Table 6. ELECTRICAL CHARACTERISTICS (continued)

Unless otherwise specified, al limits are guaranteed for  $T_A$  = 25°C,  $V_{DD}$  = 1.8 V,  $V_{IN}$  = 94 dB (SPL) and  $f_{CLK}$  = 2.4 MHz. Duty Cycle = 50% and  $C_{MIC}$  = 15 pF

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
V <sub>IH</sub>	CLOCK & SELECT Input Logic HIGH Level		1.5		V <sub>DD</sub> +0.3	V
V <sub>OL</sub>	Data Output Logic LOW Level				0.35*V <sub>DD</sub>	V
V <sub>OH</sub>	Data Output Logic HIGH Level		0.65*V <sub>DD</sub>			V
V <sub>OUT</sub>	Acoustic Overload Point (Note 8)	THD+N < 10%	120			dBSPL
t <sub>A</sub>	Time from CLOCK Transition to Data becoming Valid	On Falling Edge of CLOCK, SELECT = GND, C <sub>LOAD</sub> = 15 pF	18	43		ns
t <sub>B</sub>	Time from CLOCK Transition to Data becoming HIGH-Z	On Rising Edge of CLOCK, SELECT = GND, C <sub>LOAD</sub> = 15 pF	0	5	16	ns
t <sub>A</sub>	Time from CLOCK Transition to Data becoming Valid	On Rising Edge of CLOCK, SELECT = $V_{DD}$ , $C_{LOAD}$ = 15 pF	18	58		ns
t <sub>B</sub>	Time from CLOCK Transition to Data becoming HIGH-Z	On Falling Edge of CLOCK, SELECT = $V_{DD}$ , $C_{LOAD}$ = 15 pF	0	5	16	ns
f <sub>CLK</sub>	Input CLOCK Frequency (Note 9)	Active Mode	1.0	2.4	4.0	MHz
CLK <sub>dc</sub>	CLOCK Duty Cycle (Note 5)		40	50	60	%
t <sub>WAKEUP</sub>	Wake-Up Time (Note 10)	f <sub>CLK</sub> = 2.4 MHz		0.35	2.00	ms
t <sub>FALLASLEAP</sub>	Fall-Asleep Time (Note 11)	f <sub>CLK</sub> = 2.4 MHz	0	0.01	1.00	ms
C <sub>LOAD</sub>	Load Capacitance on Data				100	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pseudo-random noise with triangular probability density function. Bandwidth up to 10 MHz.

5. Guaranteed by characterization. Not production tested.

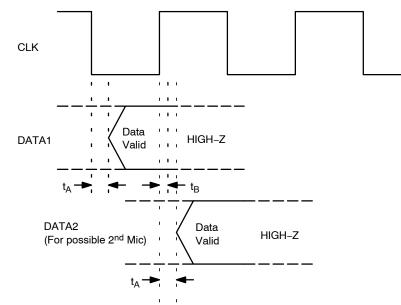
Assuming that 120 dB (SPL) is mapped to 0 dBFS.
 Assuming an input of -45 dBV.

8. Guaranteed by design. Not production tested.

9. All parameters are tested at 2.4 MHz. Frequency range guaranteed by characterization.

10. Device wakes up when  $f_{CLK} \ge 300 \text{ kHz}$ .

11. Device falls asleep when  $f_{CLK} \le 70$  kHz.



 $t_{A\ -}$  Microphone delay from clock edge to data assertion.

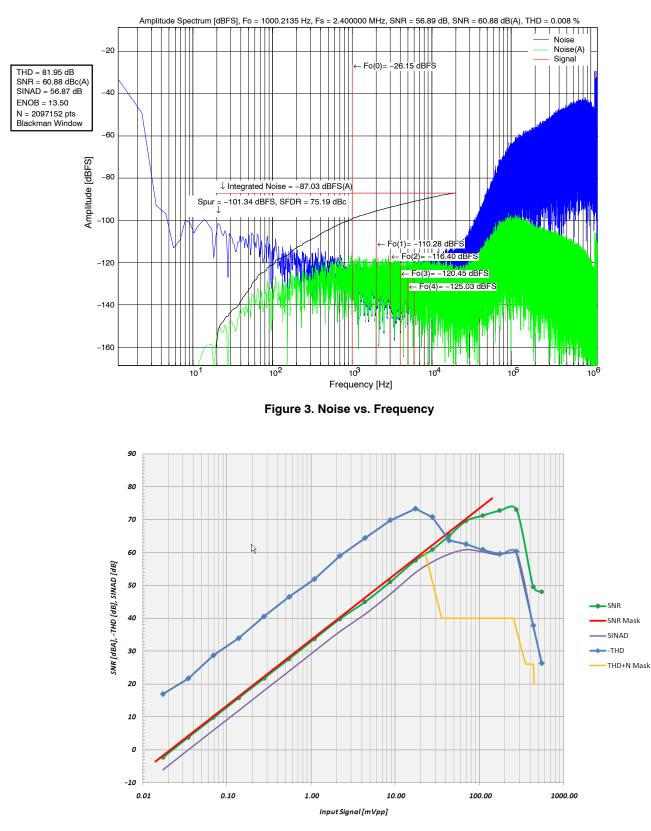
tB - Microphone delay from clock edge to high-impedance state.

 $t_A > t_B$  to have interim HIGH–Z state in both signals.

Figure 2. Interface Timing

## **TYPICAL PERFORMANCE CHARACTERISTICS**

Unless otherwise specified, all limits are guaranteed for  $T_A = 25^{\circ}C$ ,  $V_{DD} = 1.8$  V,  $V_{IN} = 94$  dB (SPL),  $f_{CLK} = 2.4$  MHz and duty Cycle = 50%.





#### TYPICAL PERFORMANCE CHARACTERISTICS (continued)

Unless otherwise specified, all limits are guaranteed for  $T_A = 25^{\circ}C$ ,  $V_{DD} = 1.8$  V,  $V_{IN} = 94$  dB (SPL),  $f_{CLK} = 2.4$  MHz and duty Cycle = 50%.

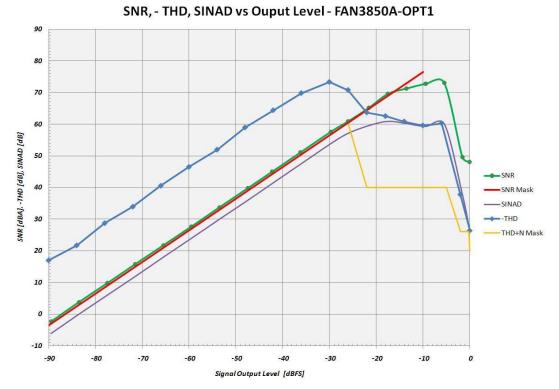


Figure 5. THD, SINAD and SNR vs. Output Level

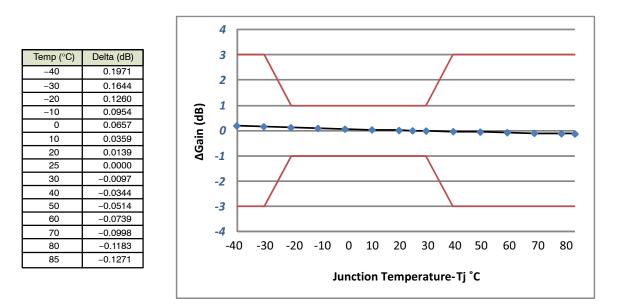


Figure 6.  $\Delta$  Gain vs. Temperature (Nominal Temperature = 25°C)

# **APPLICATIONS INFORMATION**

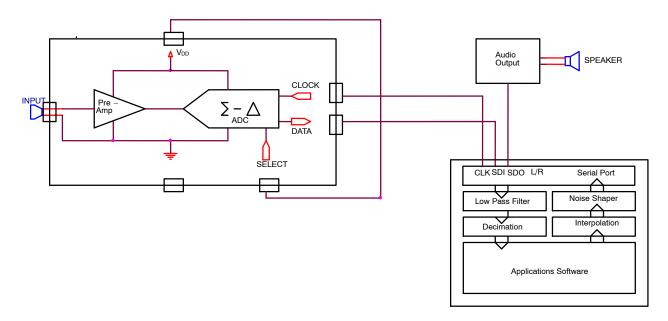


Figure 7. Mono Microphone Application Circuit

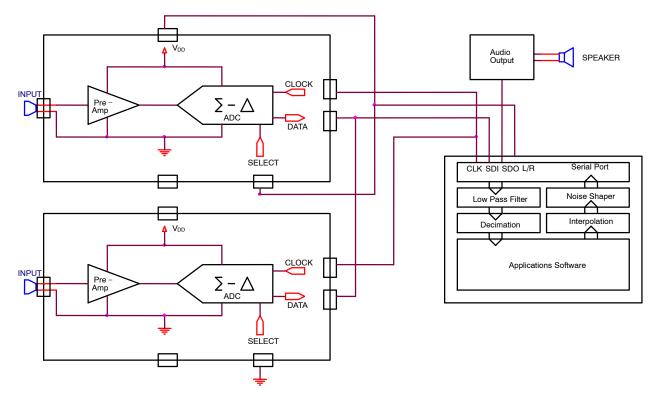


Figure 8. Stereo Microphone Application Circuit

#### APPLICATIONS INFORMATION (continued)

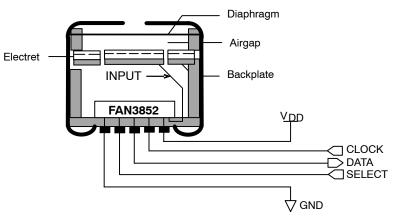


Figure 9. MIC Element Drawing

A 0.1  $\mu$ F decoupling capacitor is required for VDD. It can be located inside the microphone or on the PCB very close to the VDD pin.

Due to high input impedance, care should be taken to remove all flux used during the reflow soldering process. A 100  $\Omega$  resistance is recommended on the clock output of the device driving the FAN3852 to minimize ringing and improve signal integrity.

For optimal PSR, route a trace to the VDD pin. Do not place a VDD plane under the device.

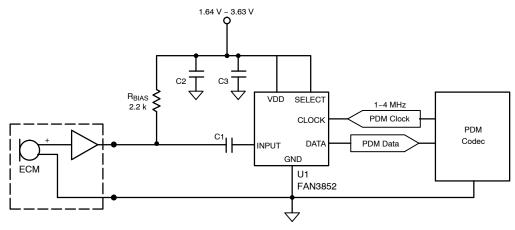
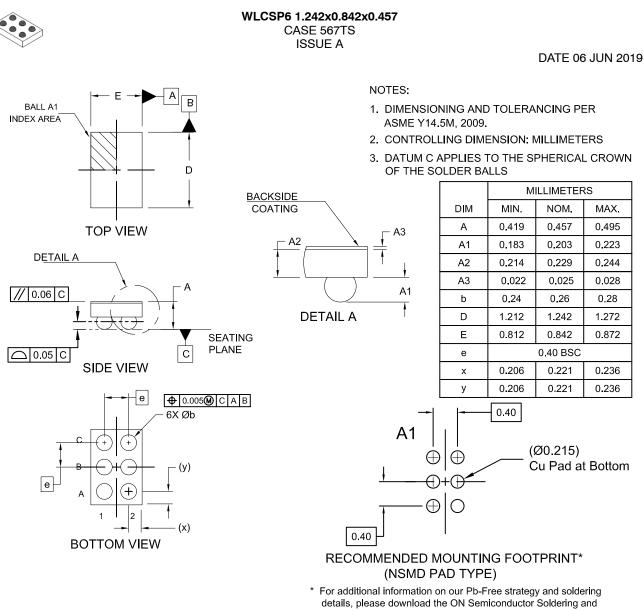


Figure 10. Example Hardware Implementation

#### Table 7. RECOMMENDED COMPONENTS

Ref Des	Qty	Description of Options	Package	Manufacturer	Mfg PIN
U1	1	FAN3852 Microphone Pre-Amplifier with Digital Output	WLCSP6	ON Semiconductor	FAN3852UC16X
C1	1	Input AC Coupling Capacitor; 1 nF/1000 pF, $\geq$ 6.3 V, low–leakage	0402	Johansen Dielectrics	500R07W102KV4T
			0402	Murata	GCM155R71H102KA37D
			0603	Taiyo Yuden	UMK107SD102KA-T
C2	1	Primary VDD Decoupling Capacitor;	0402	Samsung	CL05B104KO5NNNC
		0.1 μF, MLCC, ≥ 6.3 V	0402	Yageo	CC0402KRX7R7BB104
			0603	AVX	06033C104KAT4A
C3	1	Optional VDD Decoupling Capacitor;	0402	Samsung	CL05B103KB5VPNC
		0.01 μF, MLCC, ≥ 6.3 V	0402	Murata	GCM155R71H103KA55J
			0603	Yageo	CC0603KRX7R7BB103





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